FIG. 1

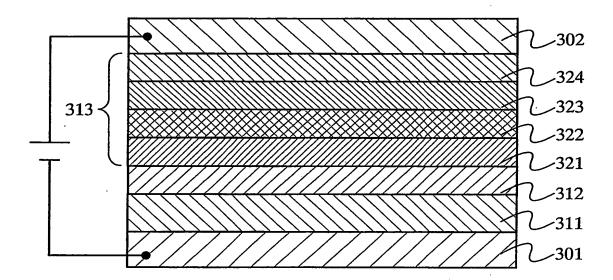


FIG. 2

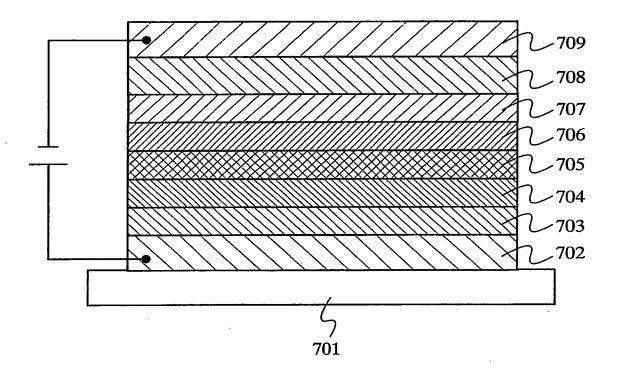


FIG. 3

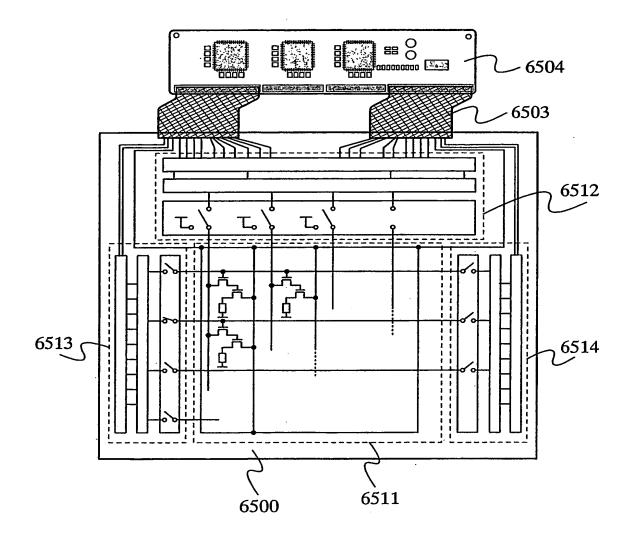


FIG. 4

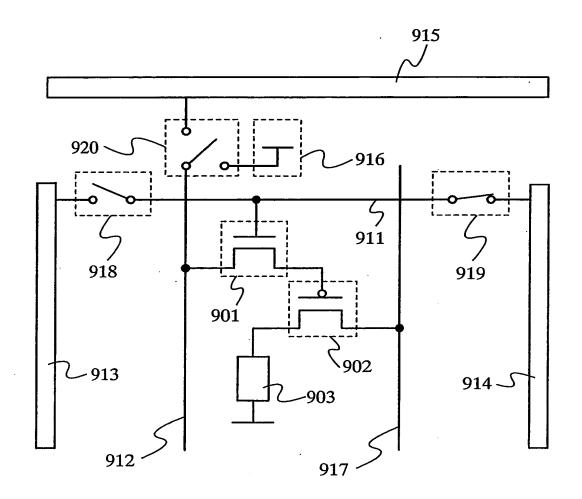
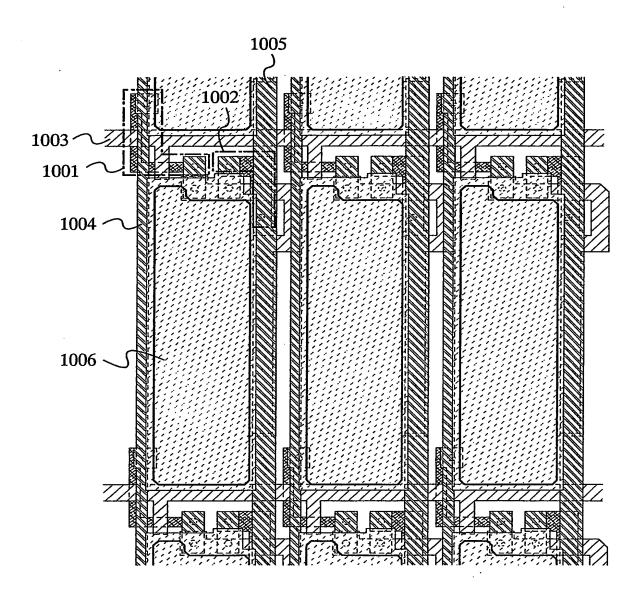
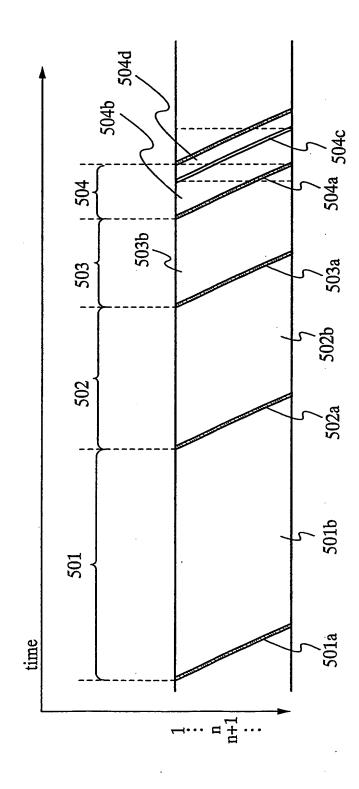


FIG. 5

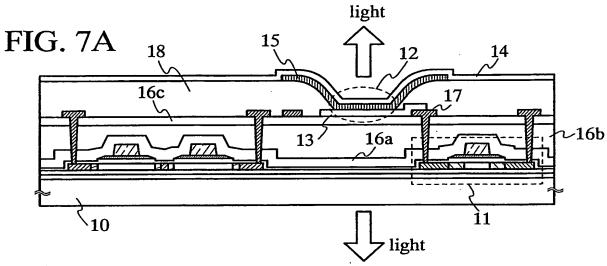


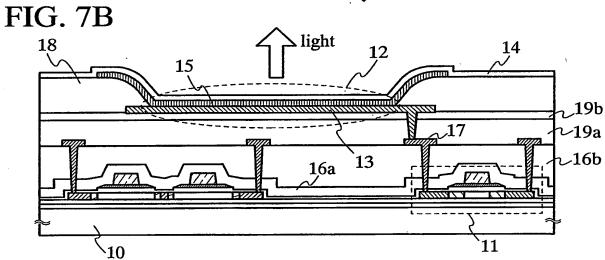


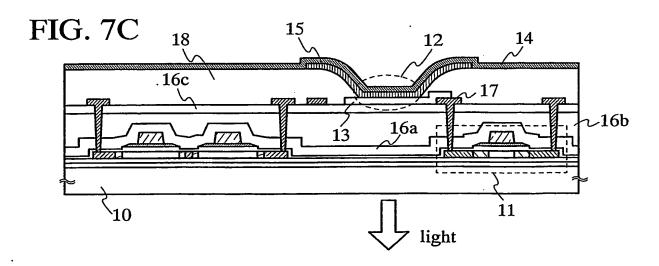


ÍG. 6

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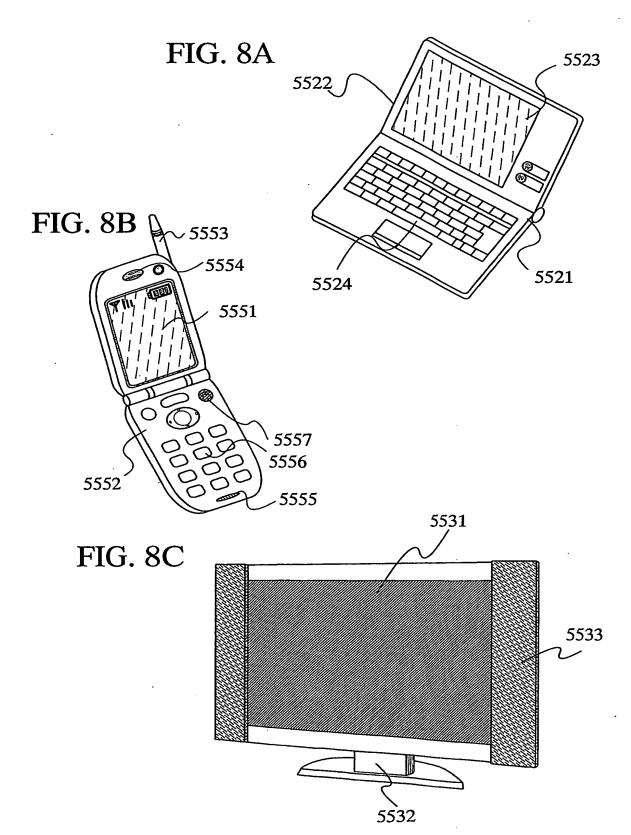


FIG. 9

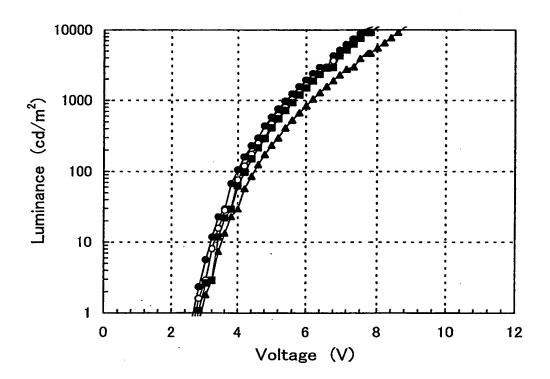
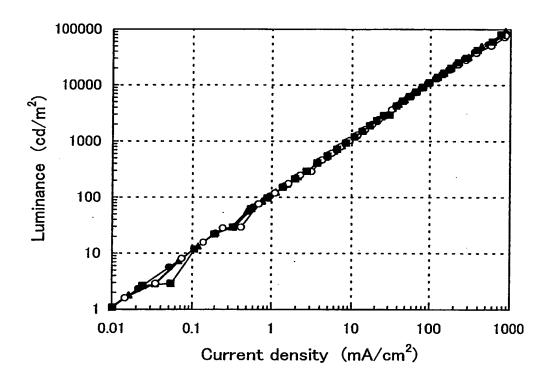


FIG. 10



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FIG. 11

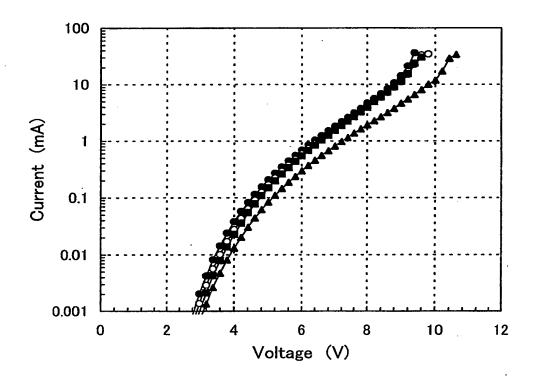


FIG. 12

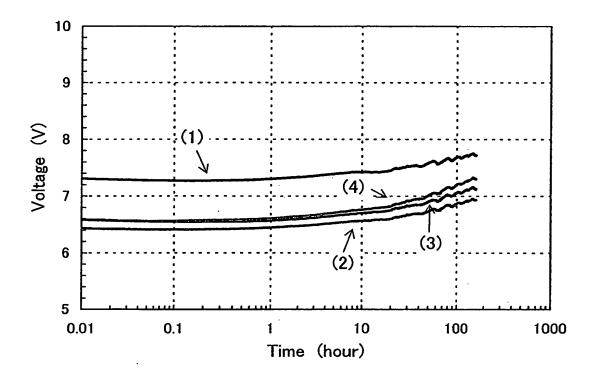


FIG. 13

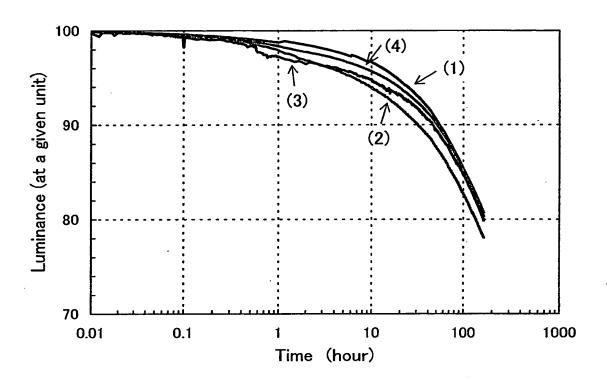
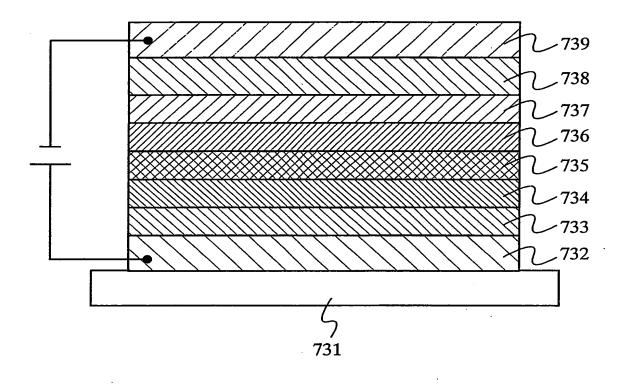


FIG. 14



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FIG. 15

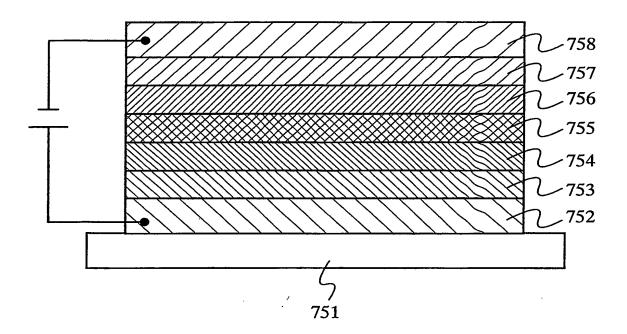


FIG. 16

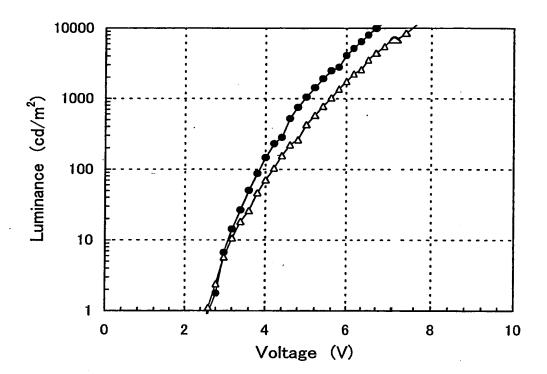


FIG. 17

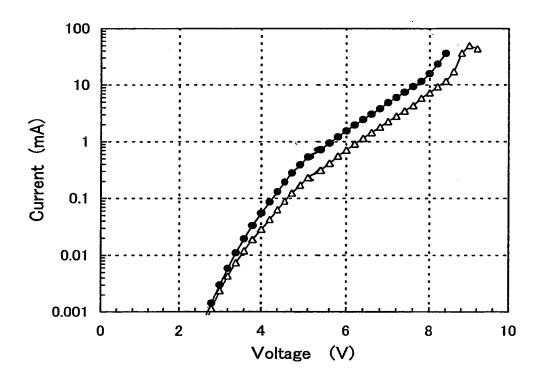


FIG. 18

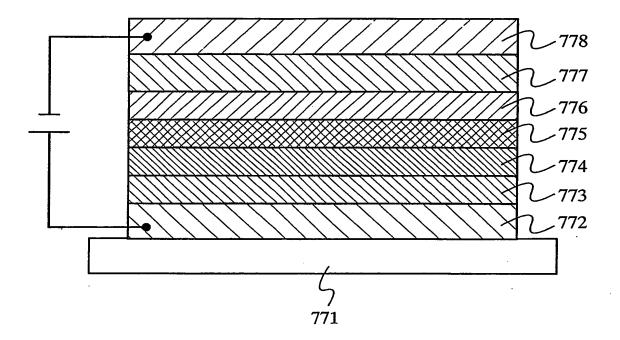


FIG. 19

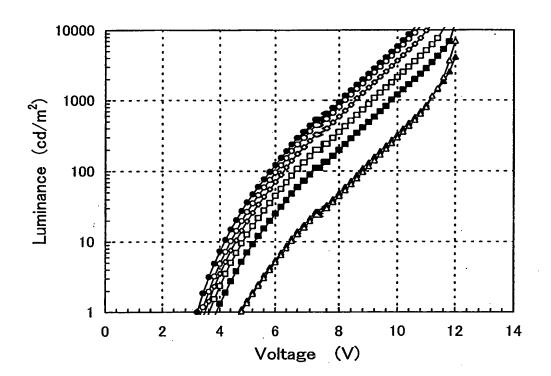


FIG. 20

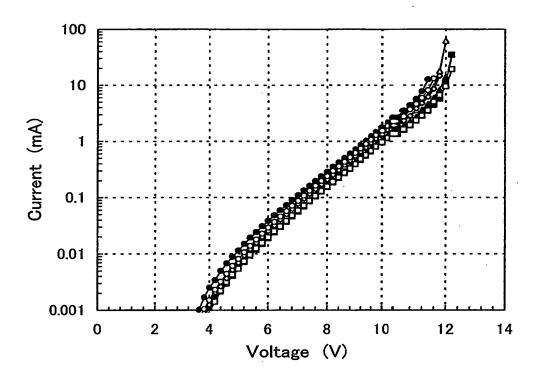


FIG. 21

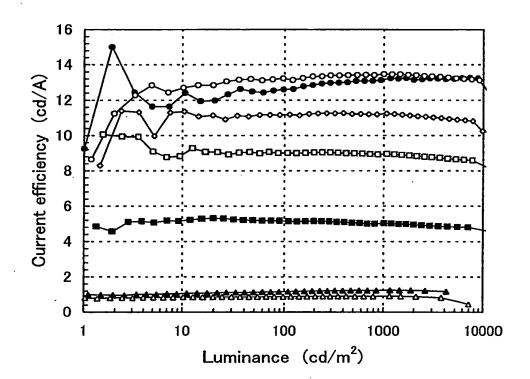


FIG. 22

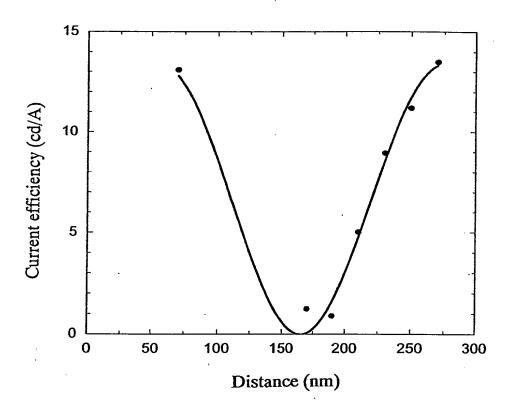


FIG. 23A

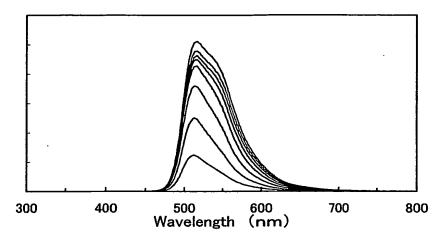


FIG. 23B

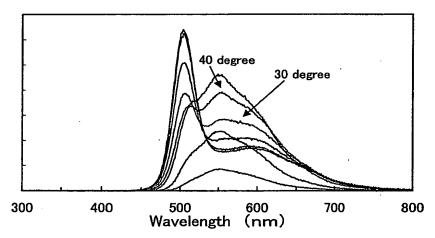


FIG. 23C

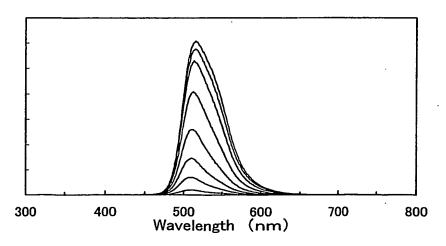


FIG. 24

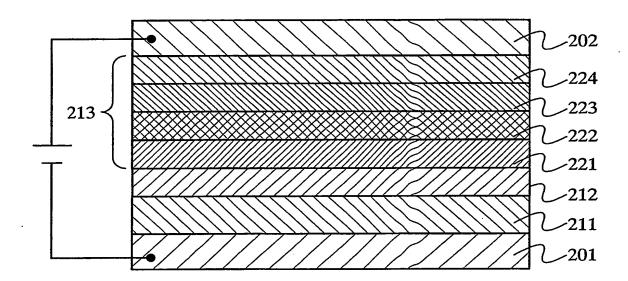


FIG. 25

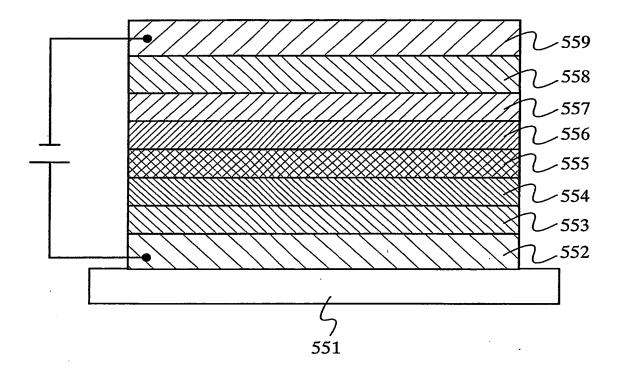
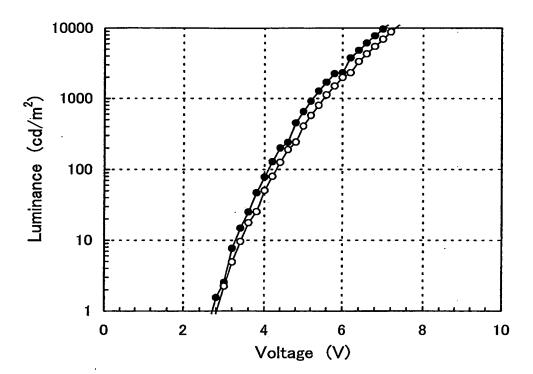


FIG. 26



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FIG. 27

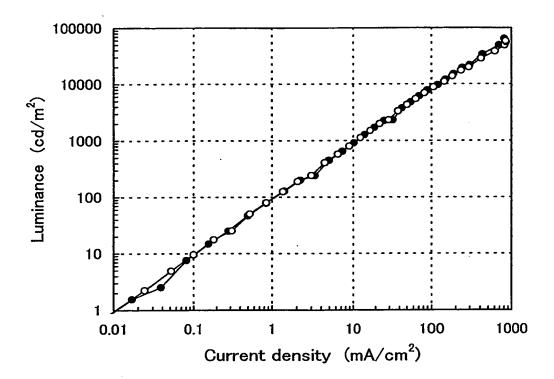
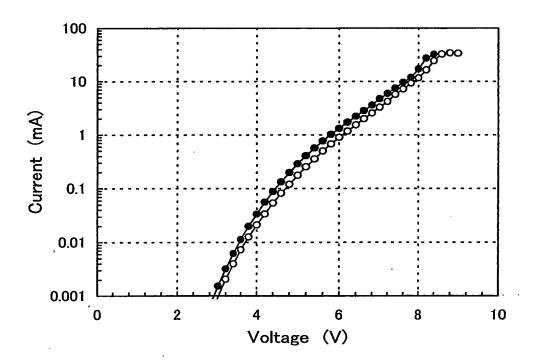
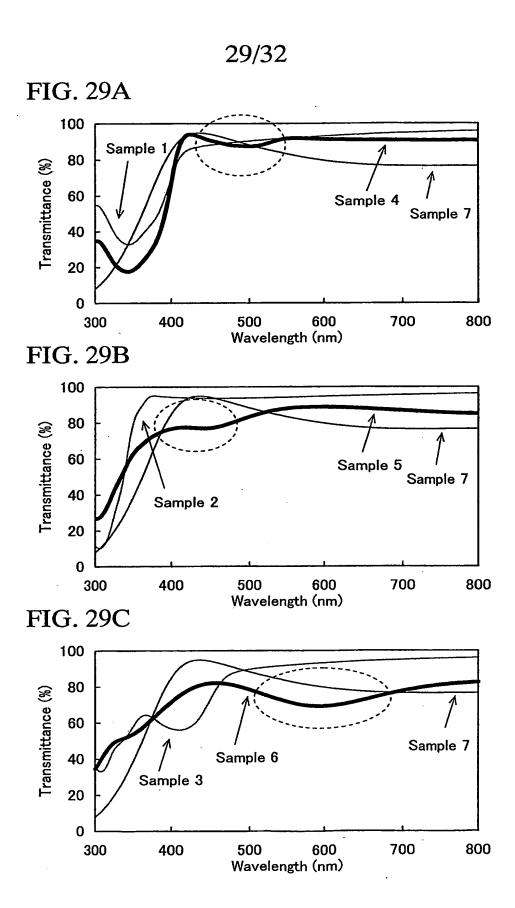


FIG. 28





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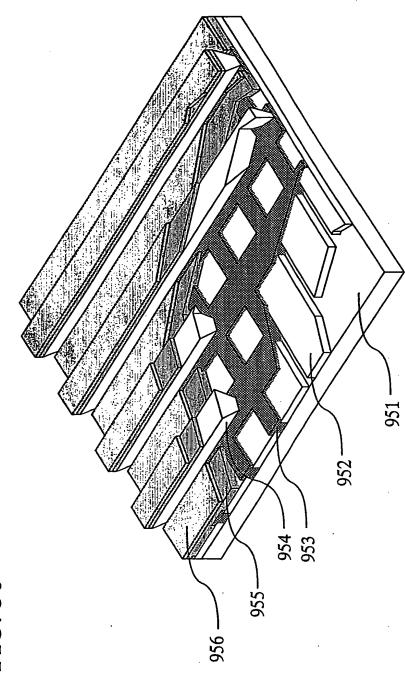


FIG. 30

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EXPLANATION OF REFERENCE

10: substrate, 11: transistor, 12: light-emitting element, 13: first electrode, 14: second electrode, 15: layer, 16: interlayer insulating film, 16a: interlayer insulating film, 16b: interlayer insulating film, 16c: interlayer insulating film, 17: wiring, 18: partition layer, 19: interlayer insulating film, 19a: interlayer insulating film, 19b: interlayer insulating film, 201: first electrode, 202: second electrode, 211: first layer, 212: second layer, 213: third layer, 221: electron transporting layer, 222: light-emitting layer, 223: hole transporting layer, 224: hole injecting layer, 301: first electrode, 302: second electrode, 311: first layer, 312: second layer, 313: third layer, 321: electron transporting layer, 322: light-emitting layer, 323: hole transporting layer, 324: hole injecting layer, 501: sub frame period, 502: sub frame period, 503: sub frame period, 504: sub frame period, 501a: write period, 501b: retention period, 502a: write period, 502b: retention period, 503a: write period, 503b: retention period, 504a: write period, 504b: retention period, 504c: erase period, 504d: non-light emitting period, 551: substrate, 552: second electrode, 553: layer, 554: layer, 555: layer, 556: layer, 557: second layer, 558: first layer, 559: first electrode, 701: substrate, 702: second electrode, 703: layer, 704: layer, 705: layer, 706: layer, 707: second layer, 708: first layer, 709: first electrode, 731: substrate, 732: second electrode, 733: layer, 734: layer, 735: layer, 736: layer, 737: second layer, 738: first layer, 739: first electrode, 751: substrate, 752: second electrode, 753: layer, 754: layer, 755: layer, 756: layer, 757: second layer, 758: first electrode, 771:

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substrate, 772: second electrode, 773: layer, 774: layer, 775: layer, 776: second layer, 777: first layer, 778: first electrode, 901: first transistor, 902: second transistor, 903: light-emitting element, 911: gate signal line, 912: source signal line, 913: writing gate signal line driver circuit, 914: erasing gate signal line driver circuit, 915: source signal line driver circuit, 916: power source, 917: current supply line, 918: switch, 919: switch, 920: switch, 951: substrate, 952: electrode, 953: insulating layer, 954: partition layer, 955: layer, 956: electrode, 1001: first transistor, 1002: second transistor, 1003: gate signal line, 1004: source signal line, 1005: current supply line, 1006: electrode, 5521: main body, 5522: casing, 5523: display portion, 5524: keyboard, 5531: display portion, 5532: casing, 5533: speaker, 5551: display portion, 5552: main body, 5553: antenna, 5554: audio output portion, 5555: audio input portion, 5556: operation switch, 5557: operation switch, 6500: substrate, 6503: FPC (flexible printed circuit), 6504: printed wiring board (PWB), 6511: pixel portion, 6512: source signal line driver circuit, 6513: writing gate signal line driver circuit, 6514: erasing gate signal line driver circuit.